NEC

MOS FIELD EFFECT TRANSISTOR

μPA1792

SWITCHING
N- AND P-CHANNEL POWER MOS FET
INDUSTRIAL USE

DESCRIPTION

The μPA1792 is N- and P-Channel MOS Field Effect Transistors designed for Motor Drive application of HDD and so on.

FEATURES

- Low on-resistance

  N-Channel $R_{DS(on)1}$ = 26 mΩ MAX. (V_{GS} = 10 V, I_D = 3.4 A)

  $R_{DS(on)2}$ = 36 mΩ MAX. (V_{GS} = 4.5 V, I_D = 3.4 A)

  $R_{DS(on)3}$ = 42 mΩ MAX. (V_{GS} = 4.0 V, I_D = 3.4 A)

  P-Channel $R_{DS(on)1}$ = 36 mΩ MAX. (V_{GS} = –10 V, I_D = –2.9 A)

  $R_{DS(on)2}$ = 54 mΩ MAX. (V_{GS} = –4.5 V, I_D = –2.9 A)

  $R_{DS(on)3}$ = 65 mΩ MAX. (V_{GS} = –4.0 V, I_D = –2.9 A)

- Low input capacitance

  N-Channel C_{iss} = 760 pF TYP.

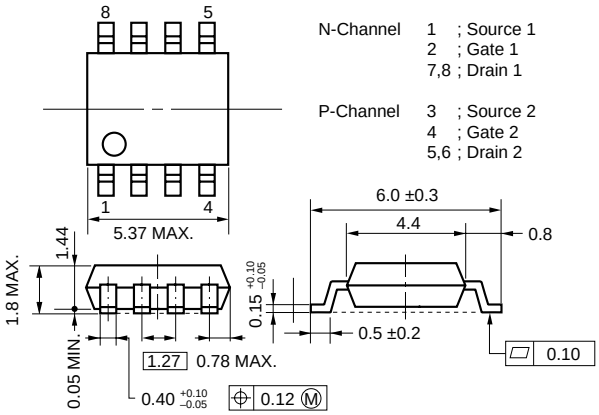
  P-Channel C_{iss} = 900 pF TYP.

- Built-in G-S protection diode
- Small and surface mount package (Power SOP8)

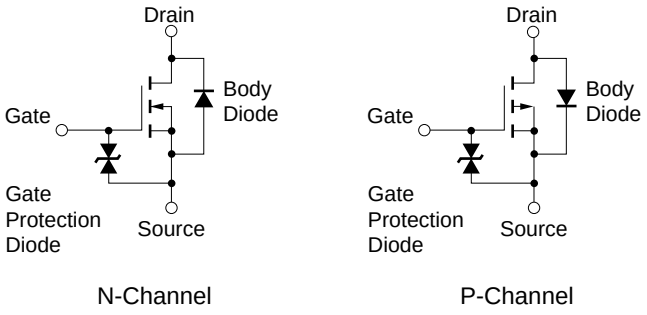
ORDERING INFORMATION

PART NUMBER	PACKAGE
μPA1792G	Power SOP8

PACKAGE DRAWING (Unit : mm)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, All terminals are connected.)

PARAMETER	SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Drain to Source Voltage (V_{GS} = 0 V)	V_{DSS}	30	–30	V
Gate to Source Voltage (V_{DS} = 0 V)	V_{GSS}	± 20	∓ 20	V
Drain Current (DC)	$I_{D(DC)}$	± 6.8	∓ 5.8	A
Drain Current (pulse) Note1	$I_{D(pulse)}$	± 27.2	∓ 23.2	A
Total Power Dissipation (1 unit) Note2	P_T	1.7		W
Total Power Dissipation (2 unit) Note2	P_T	2.0		W
Channel Temperature	T_{ch}	150		°C
Storage Temperature	T_{stg}	–55 to +150		°C

Notes 1. PW ≤ 10 μs, Duty Cycle ≤ 1%

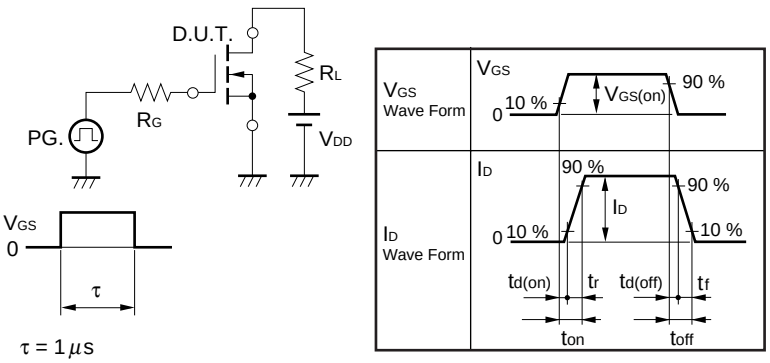
2. Mounted on ceramic substrate of 2000 mm^2 × 1.6 mm, T_A = 25°C

ELECTRICAL CHARACTERISTICS (T_A = 25°C, All terminals are connected.)

N-CHANNEL

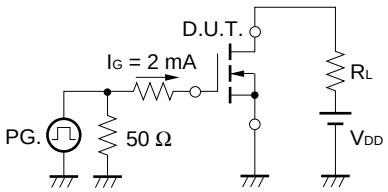
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	$R_{DS(on)1}$	V_{GS} = 10 V, I_D = 3.4 A		20.5	26	mΩ
	$R_{DS(on)2}$	V_{GS} = 4.5 V, I_D = 3.4 A		27	36	mΩ
	$R_{DS(on)3}$	V_{GS} = 4.0 V, I_D = 3.4 A		31	42	mΩ
Gate to Source Cut-off Voltage	$V_{GS(off)}$	V_{DS} = 10 V, I_D = 1 mA	1.5	2.1	2.5	V
Forward Transfer Admittance	$\|y_{fs}\|$	V_{DS} = 10 V, I_D =3.4 A	3.0	7.5		S
Drain Leakage Current	I_{DSS}	V_{DS} = 30 V, V_{GS} = 0 V			10	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±16 V, V_{DS} = 0 V			±10	μA
Input Capacitance	C_{iss}	V_{DS} = 10 V		760		pF
Output Capacitance	C_{oss}	V_{GS} = 0 V		250		pF
Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		95		pF
Turn-on Delay Time	$t_{d(on)}$	I_D = 3.4 A		20		ns
Rise Time	t_r	$V_{GS(on)}$ = 10 V		140		ns
Turn-off Delay Time	$t_{d(off)}$	V_{DD} = 15 V		50		ns
Fall Time	t_f	R_G = 10 Ω		30		ns
Total Gate Charge	Q_G	I_D = 6.8 A		14		nC
Gate to Source Charge	Q_{GS}	V_{DD} = 24 V		2		nC
Gate to Drain Charge	Q_{GD}	V_{GS} = 10 V		5		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 6.8 A, V_{GS} = 0 V		0.86		V
Reverse Recovery Time	t_{rr}	I_F = 6.8 A, V_{GS} = 0 V		30		ns
Reverse Recovery Charge	Q_{rr}	di/dt = 100 A / μs		20		nC

TEST CIRCUIT 1 SWITCHING TIME



τ = 1 μs
Duty Cycle ≤ 1 %

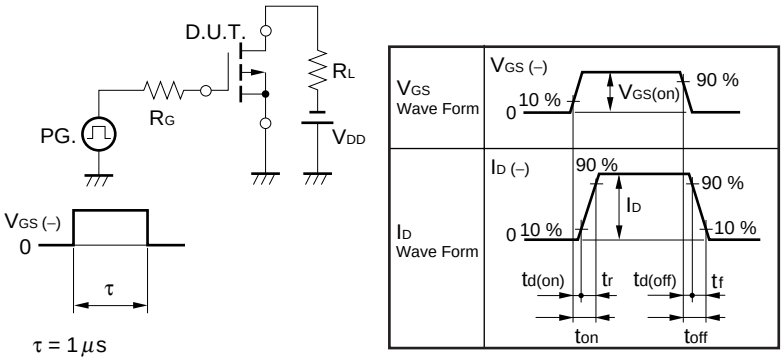
TEST CIRCUIT 2 GATE CHARGE



P-CHANNEL

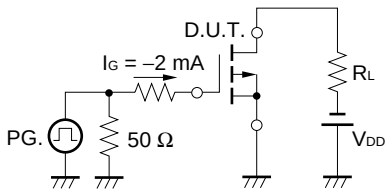
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	$R_{DS(on)1}$	V_{GS} = –10 V, I_D = –2.9 A		30	36	mΩ
	$R_{DS(on)2}$	V_{GS} = –4.5 V, I_D = –2.9 A		43	54	mΩ
	$R_{DS(on)3}$	V_{GS} = –4.0 V, I_D = –2.9 A		49	65	mΩ
Gate to Source Cut-off Voltage	$V_{GS(off)}$	V_{DS} = –10 V, I_D = –1 mA	–1.5	–2.0	–2.5	V
Forward Transfer Admittance	$\|y_{fs}\|$	V_{DS} = –10 V, I_D = –2.9 A	3.5	8.0		S
Drain Leakage Current	I_{DSS}	V_{DS} = –30 V, V_{GS} = 0 V			–1	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ∓16 V, V_{DS} = 0 V			∓10	μA
Input Capacitance	C_{iss}	V_{DS} = –10 V		900		pF
Output Capacitance	C_{oss}	V_{GS} = 0 V		300		pF
Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		120		pF
Turn-on Delay Time	$t_{d(on)}$	I_D = –2.9 A		23		ns
Rise Time	t_r	$V_{GS(on)}$ = –10 V		220		ns
Turn-off Delay Time	$t_{d(off)}$	V_{DD} = –15 V		90		ns
Fall Time	t_f	R_G = 10 Ω		70		ns
Total Gate Charge	Q_G	I_D = –5.8 A		17		nC
Gate to Source Charge	Q_{GS}	V_{DD} = –24 V		2.5		nC
Gate to Drain Charge	Q_{GD}	V_{GS} = –10 V		4.0		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 5.8 A, V_{GS} = 0 V		0.85		V
Reverse Recovery Time	t_{rr}	I_F = 5.8 A, V_{GS} = 0 V		40		ns
Reverse Recovery Charge	Q_{rr}	di/dt = 100 A / μs		30		nC

TEST CIRCUIT 1 SWITCHING TIME



τ = 1 μs
Duty Cycle ≤ 1 %

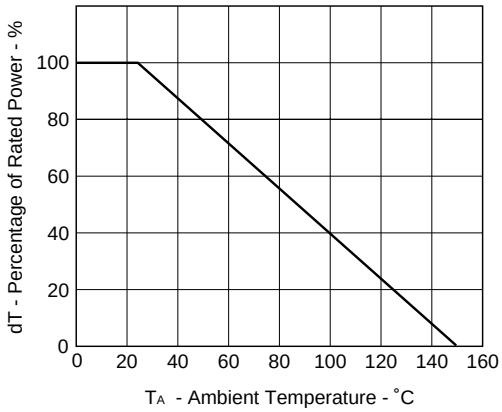
TEST CIRCUIT 2 GATE CHARGE



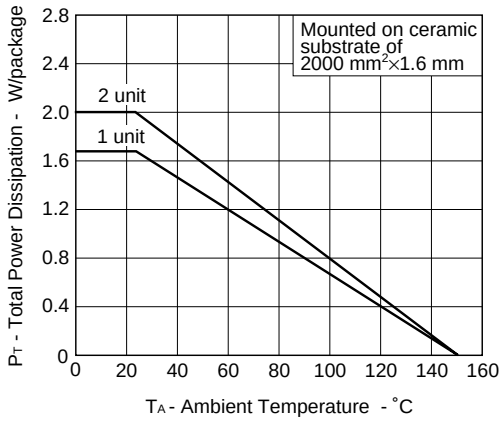
TYPICAL CHARACTERISTICS (T_A = 25°C)

A) N-Channel

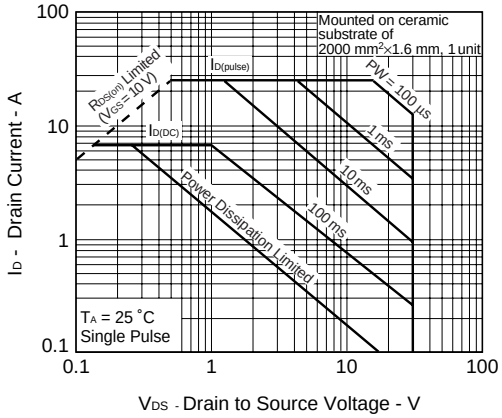
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



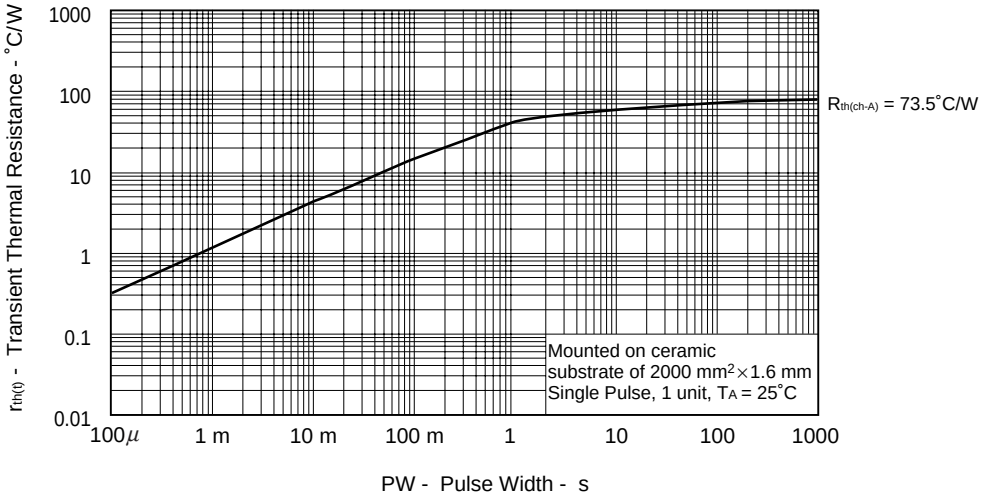
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA

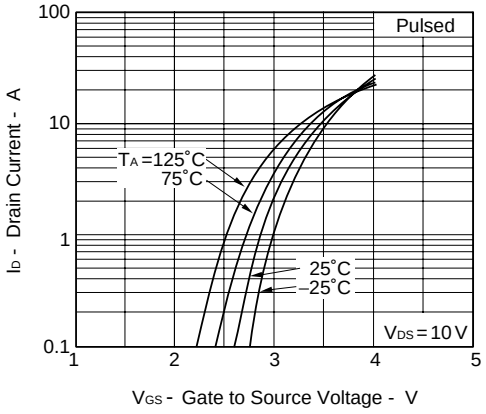


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

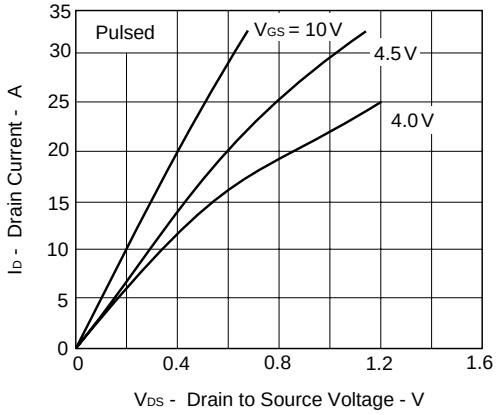


A) N-Channel

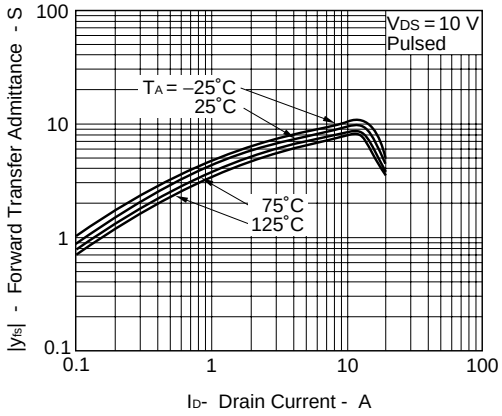
FORWARD TRANSFER CHARACTERISTICS



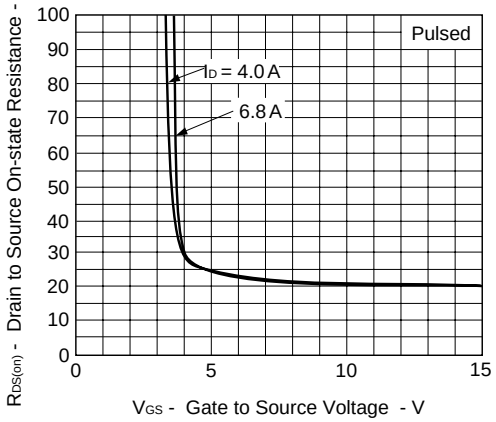
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



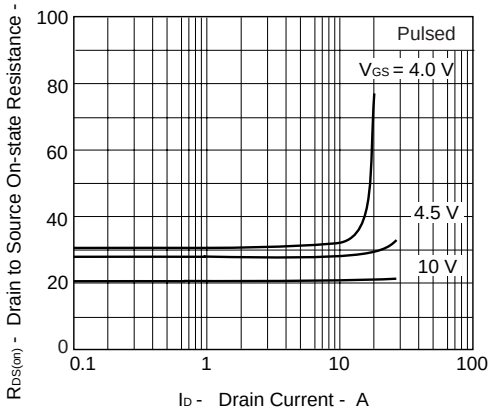
FORWARD TRANSFER ADMITTANCE vs.
DRAIN CURRENT



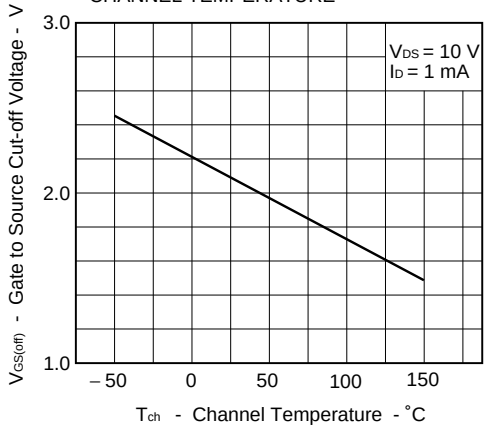
DRAIN TO SOURCE ON-STATE RESISTANCE vs.
GATE TO SOURCE VOLTAGE



DRAIN TO SOURCE ON-STATE
RESISTANCE vs. DRAIN CURRENT

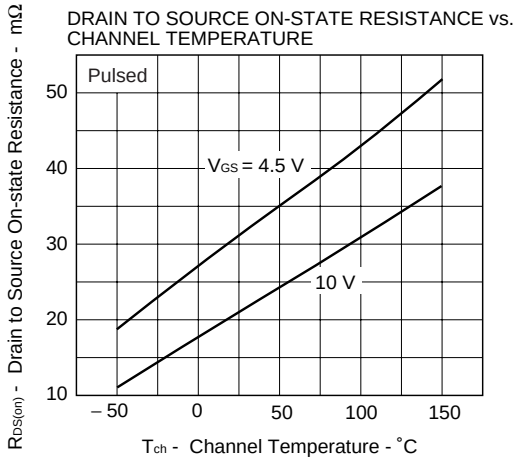


GATE TO SOURCE CUT-OFF VOLTAGE vs.
CHANNEL TEMPERATURE

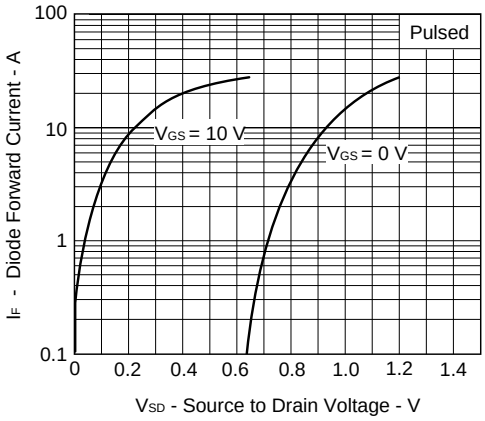


A) N-Channel

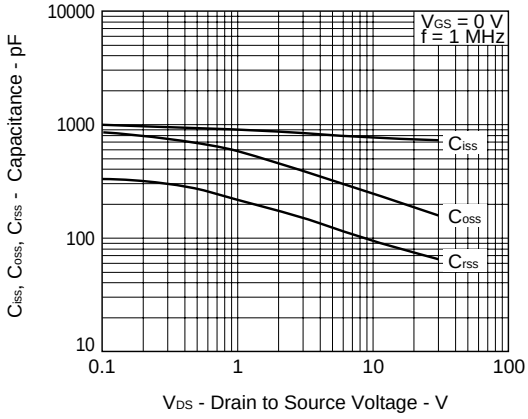
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



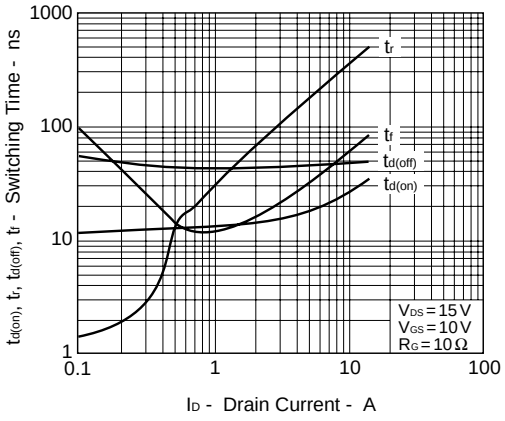
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



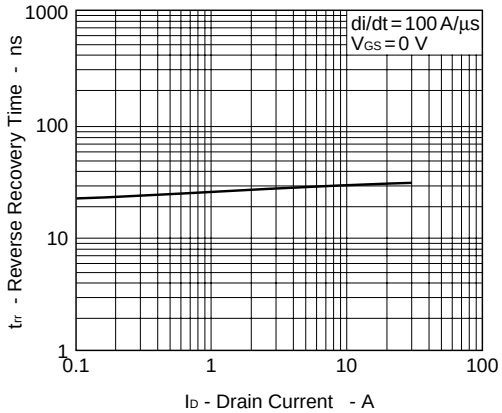
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



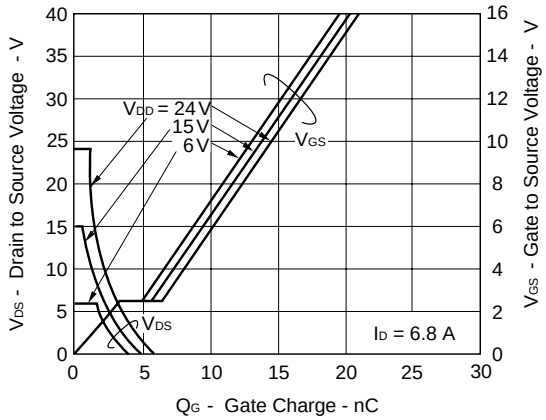
SWITCHING CHARACTERISTICS



REVERSE RECOVERY TIME vs. DRAIN CURRENT

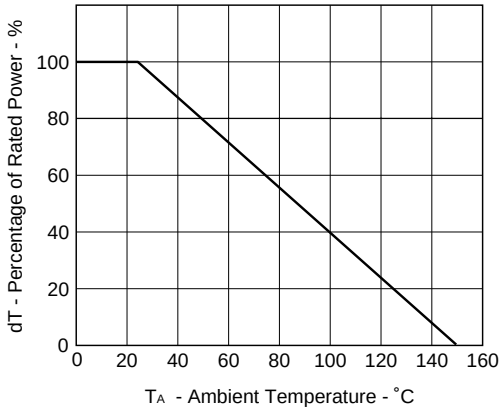


DYNAMIC INPUT/OUTPUT CHARACTERISTICS

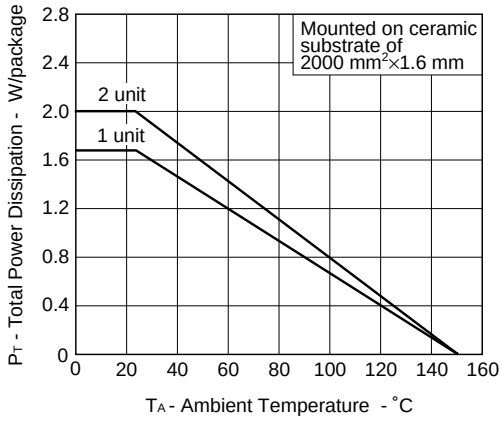


B) P-Channel

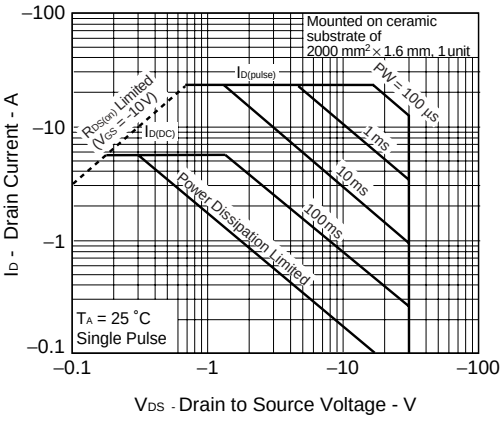
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



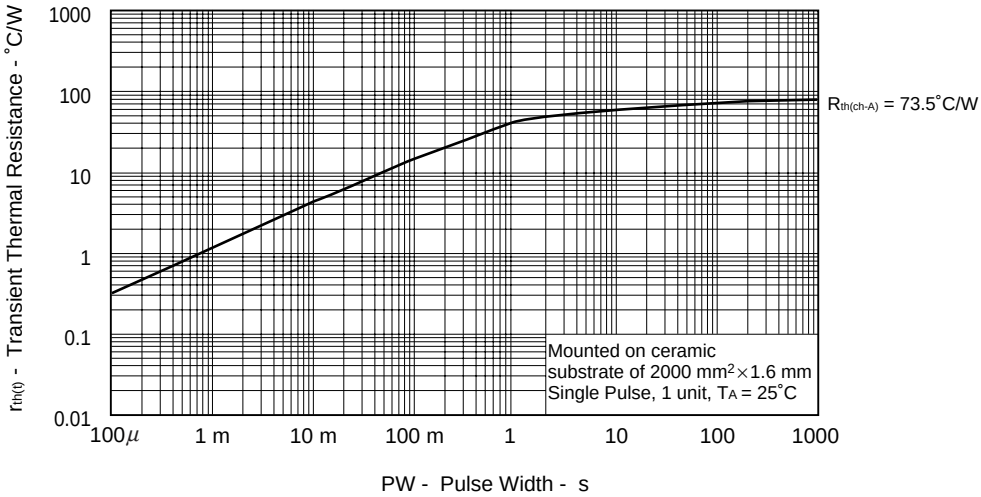
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA

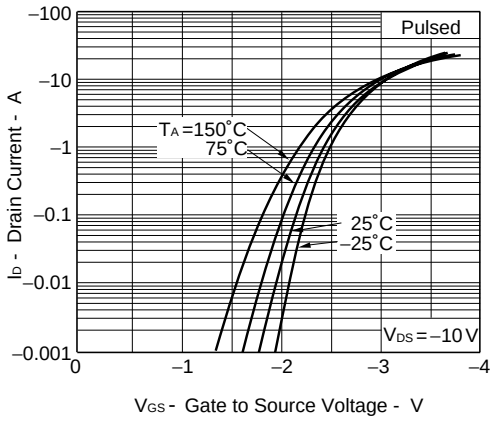


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

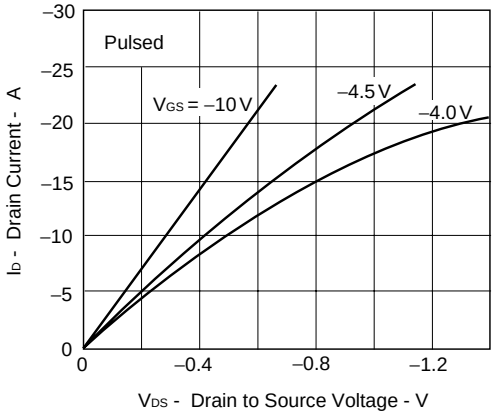


B) P-Channel

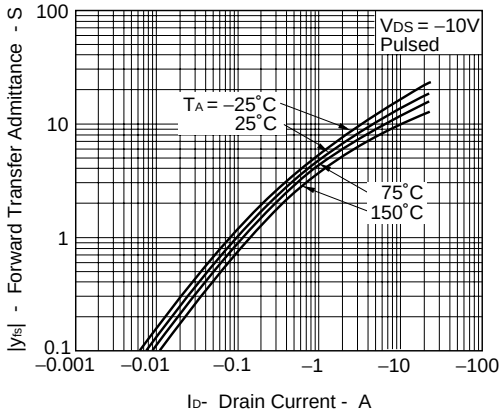
FORWARD TRANSFER CHARACTERISTICS



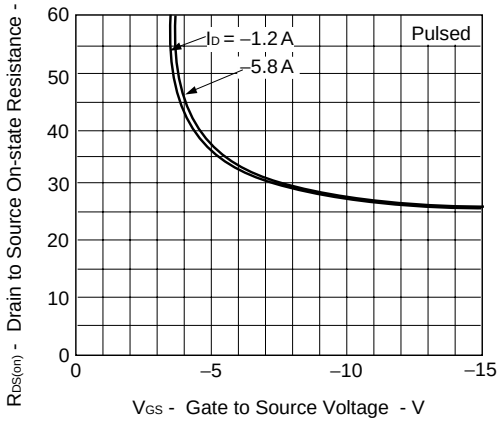
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



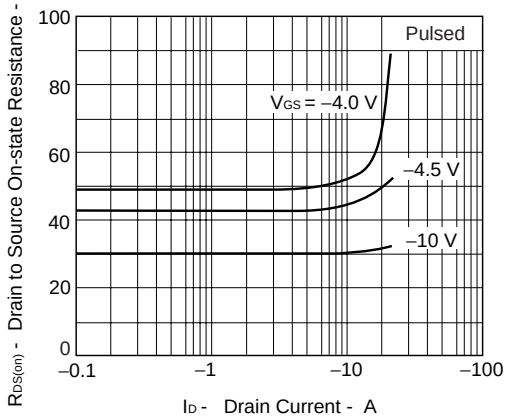
FORWARD TRANSFER ADMITTANCE vs.
DRAIN CURRENT



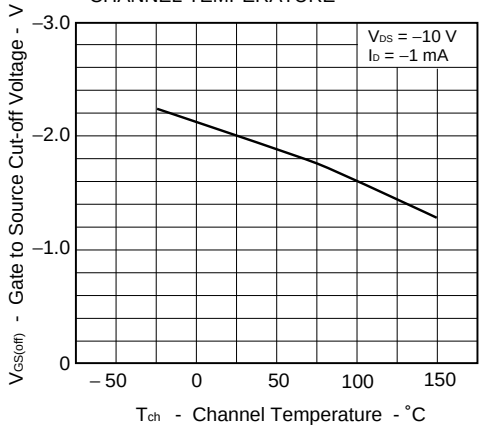
DRAIN TO SOURCE ON-STATE RESISTANCE vs.
GATE TO SOURCE VOLTAGE



DRAIN TO SOURCE ON-STATE
RESISTANCE vs. DRAIN CURRENT

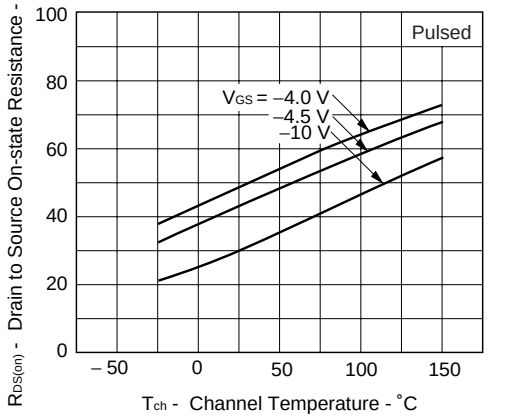


GATE TO SOURCE CUT-OFF VOLTAGE vs.
CHANNEL TEMPERATURE

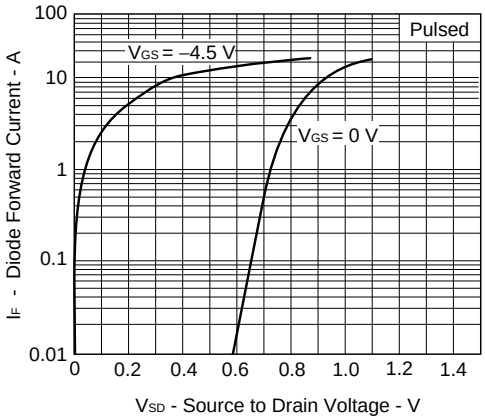


B) P-Channel

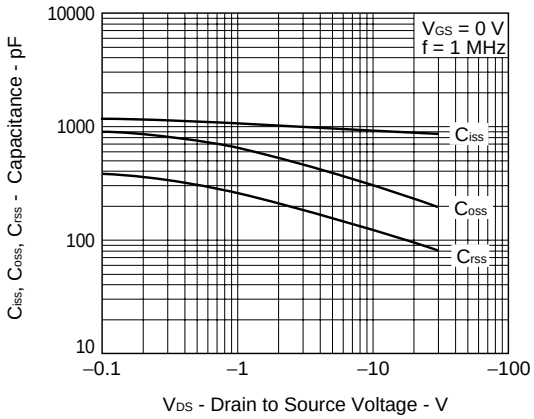
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



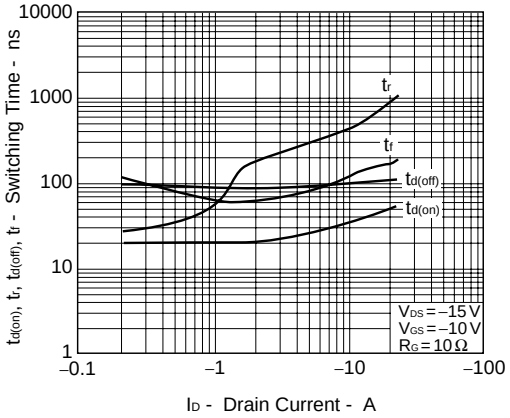
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



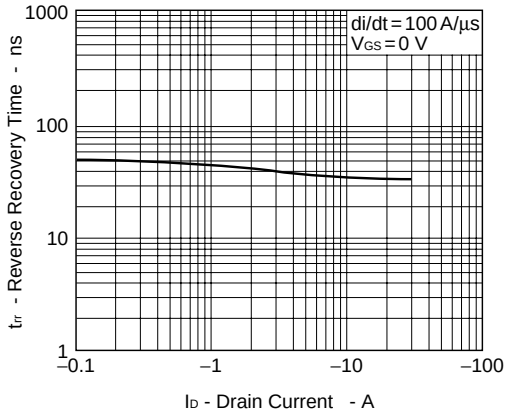
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



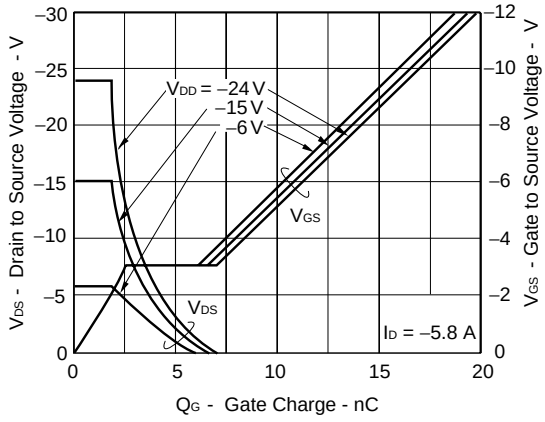
SWITCHING CHARACTERISTICS



REVERSE RECOVERY TIME vs. DRAIN CURRENT



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



[MEMO]

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